

[Your Name]  
[Your Address]  
[City, State, Zip Code]  
[Email Address]  
[Phone Number]  
[Date]

[Recipient Name]  
[Recipient Title]  
[Recipient Organization]  
[Recipient Address]  
[City, State, Zip Code]

Dear [Recipient Name],

Subject: Patent Application for VLSI Technology

I hope this letter finds you well. I am writing to formally submit a patent application for a novel VLSI (Very Large Scale Integration) technology that I have developed.

**\*\*Title of the Invention:\*\***

[Title of your invention]

**\*\*Field of Invention:\*\***

This invention relates to [briefly describe the field and application of your invention].

**\*\*Background:\*\***

[Provide a brief overview of the current state of the technology and the problems that your invention addresses.]

**\*\*Summary of the Invention:\*\***

The invention provides [summarize the key aspects and advantages of your invention].

**\*\*Detailed Description:\*\***

1. **\*\*Technical Specifications:\*\***

- [List the main technical specifications of your invention.]

2. **\*\*Figures and Drawings:\*\***

- [Mention any accompanying figures or drawings that illustrate the invention.]

3. **\*\*Claims:\*\***

- Claim 1: [First claim]

- Claim 2: [Second claim]

- [Additional claims as necessary]

I have enclosed the necessary documentation, including the patent forms, drawings, and a detailed description of the invention. Please confirm the receipt of this application and do not hesitate to reach out if any further information or clarification is required.

Thank you for considering my application. I look forward to your response.

Sincerely,

[Your Signature (if sending a hard copy)]

[Your Printed Name]

[Your Title/Position (if applicable)]

[Your Company Name (if applicable)]